## **MA4X160A** (MA160A)

## Silicon epitaxial planar type

### For switching circuits

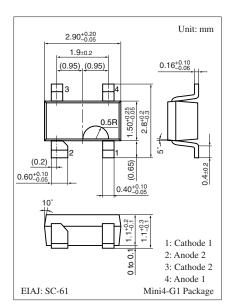
#### ■ Features

- Two isolated elements contained in one package, allowing highdensity mounting
- Centrosymmetrical wiring, allowing to free from the taping direction
- Short reverse recovery time t<sub>rr</sub>
- Small terminal capacitance C<sub>t</sub>

## ■ Absolute Maximum Ratings $T_a = 25$ °C

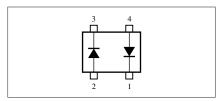
Parameter		Symbol	Rating	Unit
Reverse voltage		$V_R$	80	V
Repetitive peak reverse voltage		V <sub>RRM</sub>	80	V
Forward current	Single	$I_{F(AV)}$	100	mA
(Average)	Series		75	
Repetitive peak	Single	$I_{FRM}$	225	mA
forward current	Series		170	
Non-repetitive peak	Single	$I_{FSM}$	500	mA
forward surge current *	Series		375	
Junction temperature		T <sub>j</sub>	150	°C
Storage temperature		$T_{stg}$	-55 to +150	°C





#### Marking Symbol: M1E

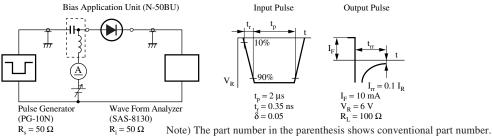
#### Internal Connection

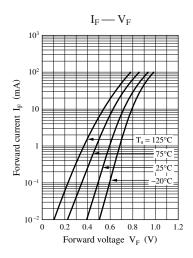


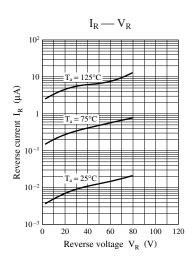
### ■ Electrical Characteristics $T_a = 25$ °C $\pm 3$ °C

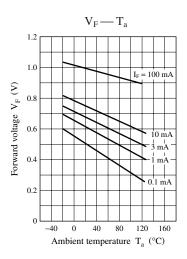
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	V <sub>F</sub>	$I_F = 100 \text{ mA}$		0.95	1.20	V
Reverse voltage	$V_R$	$I_R = 100 \mu A$	80			V
Reverse current	$I_R$	V <sub>R</sub> = 75 V			0.1	μΑ
Terminal capacitance	C <sub>t</sub>	$V_R = 0 V, f = 1 MHz$		0.9	2.0	pF
Reverse recovery time *	t <sub>rr</sub>	$I_F = 10 \text{ mA}, V_R = 6 \text{ V}$			3	ns
		$I_{rr} = 0.1 I_{R}, R_{L} = 100 \Omega$				

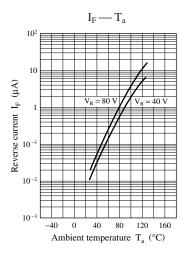
- Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
  - 2. Absolute frequency of input and output is 100 MHz.
  - 3. \*: t<sub>rr</sub> measurement circuit

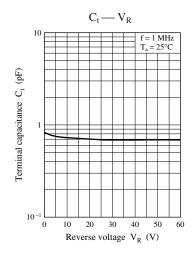


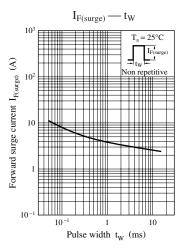












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